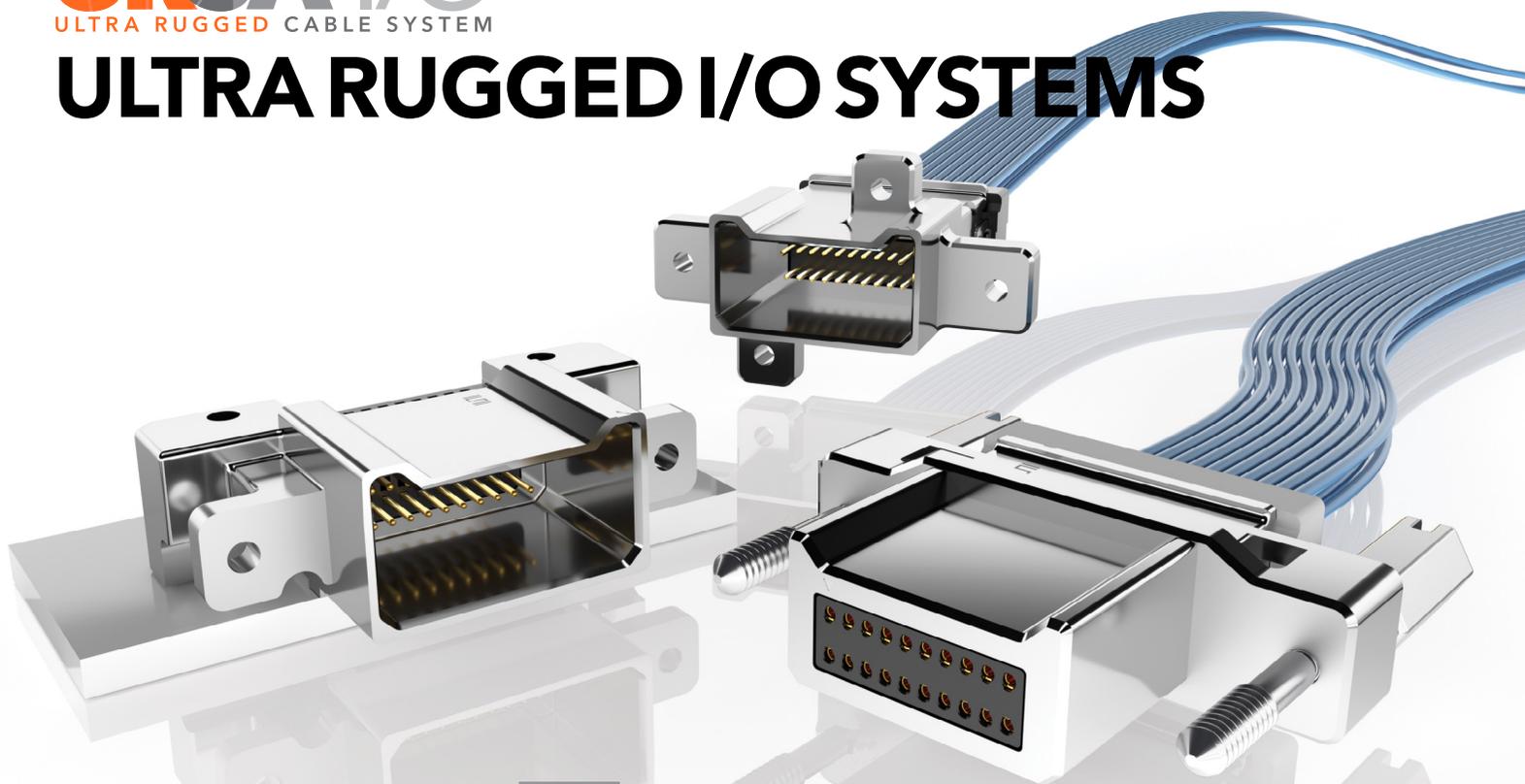


ULTRA RUGGED I/O SYSTEMS



FEATURES & BENEFITS

MAX
3.8
A m p s

- Small form factor
- Four points of contact for a reliable connection and high mating cycles
- Up to 40 positions per row
- Cable-to-cable & cable-to-board solutions
- EMI shielding limits signal degradation and optimizes performance
- Through-hole or surface mount
- 28 & 30 AWG cable
- Availability of contacts (high-speed, RF, power) in 1 to 5 block configurations (See page 231)



Shown actual size at 20 total positions



Hyper Claw™ Hyperboloid-type contact for extreme high mating cycles



Extreme density with up to 1,450 total I/Os in a 1RU panel (29 cables at 50 total I/Os each)

KEY SPECIFICATIONS

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	SHIELD MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING
P1PD(X), B1SD(X), P1M	Liquid Crystal Polymer	Beryllium Copper	Zinc Alloy	Au over 50 μ" (1.27 μm) Ni	-10 °C to +80 °C (PVC) -40 °C to +125 °C (*Teflon™ Fluoropolymer)	3.8 A per pin (2 pins powered)	200 VAC/ 282 VDC
B1SM		Copper Alloy		50 μ" (1.27 μm) Au center contact			
P1SM				30 μ" (0.76 μm) Au center contact			

*Teflon™ is a trademark of The Chemours Company FC, LLC used under license by Samtec.

(1.00 mm) .0394" PITCH • NON-PANEL MOUNT I/O CABLE/COMPONENTS

SERIES	NO. OF POSITIONS	WIRE GAUGE	COLOR CODE	PLATING	ASSEMBLED LENGTH	EMI SHIELD	PINOUT
--------	------------------	------------	------------	---------	------------------	------------	--------

B1SD
= Double Row
Non-Panel Mount
PVC Cable

B1SDT
= Double Row
Non-Panel Mount
Blue *Teflon™
Fluoropolymer Cable

**-10, -15,
-25, -30**
(Per Row)

-28
= 28 AWG

-30
= 30 AWG

(Leave blank for standard wire)

C
= Color Code Wire
(Not available with B1SDT)

-H
= 30 μm
(0.76 μm)
Gold on
contact area,
Gold flash
on tail

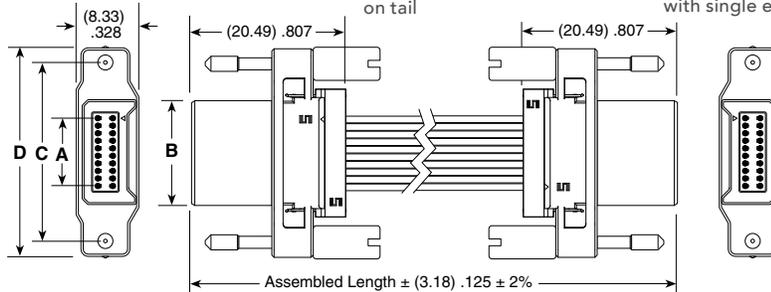
-"XX.X"
= Length in
inches
06.0"
(152.4 mm)
minimum

(Leave blank for
non-EMI shield)

-E
= EMI Shield
(Not available
with single ended)

(Leave
blank for
single
ended)

- 1**
= Pin 1 to
Pin 1
- 2**
= Pin 1 to
Pin 2
- 3**
= Pin 1 to
Pin N
- 4**
= Pin 1 to
Pin N-1



B1SDX-10-XXX-H-XX.X-3 SHOWN

NO. OF POSITIONS	A	B	C	D
-10	(9.00) .354	(13.94) .549	(23.75) .935	(27.75) 1.093
-15	(14.00) .551	(18.94) .746	(28.75) 1.132	(32.75) 1.289
-25	(24.00) .945	(28.94) 1.139	(38.75) 1.526	(42.75) 1.683
-30	(29.00) 1.142	(33.94) 1.336	(43.75) 1.722	(47.75) 1.880

*Teflon™ is a trademark of The Chemours Company FC, LLC used under license by Samtec.

Notes:
Teflon™ Fluoropolymer Cable is intended for crimp only. Contact Samtec for solderable cable applications.

Some lengths, styles and options are non-standard, non-returnable.

B1SD, B1SDT
Cable Mates:
P1PD, P1PDT
Board Mates:
P1M



B1SD & B1SDT CABLE HOLDER (Required for use with IBT1)

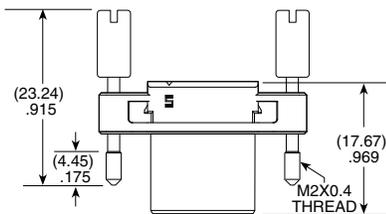
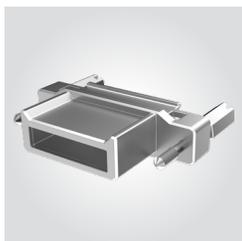
SERIES	NUMBER OF POSITIONS
B1SDR	-10, -15, -25, -30

View complete specifications at: samtec.com?B1SD & samtec.com?B1SDT

B1SDS	NO. OF POSITIONS	N	OPTION
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-10, -15, -25, -30

-CS
= Captive
Screw



NO. OF POSITIONS	A
-10	(27.75) 1.093
-15	(32.75) 1.289
-25	(42.75) 1.683
-30	(47.75) 1.880

Note:
Some lengths, styles and options are non-standard, non-returnable.

TOOLING

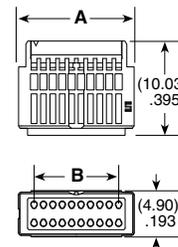
Hand Tool:
CAT-HT-508-2830-12

Mini Applicator:
CAT-MC-508-2830-XX-03

For more tooling information, visit samtec.com/tooling

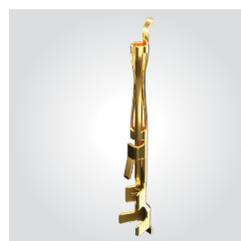
IBT1	NO. OF POSITIONS	1
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-10, -15, -25, -30

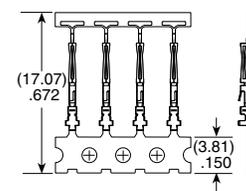


NO. OF POSITIONS	A	B
-10	(12.290) .484	(9.00) .354
-15	(17.290) .681	(14.00) .551
-25	(27.290) 1.074	(24.00) .945
-30	(32.290) 1.271	(29.00) 1.142

CC508	01	PLATING	PACKAGING
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-H
= 30 μm (0.76 μm)
Gold on contact area,
Gold flash on tail



-R
= Full Reel
(25,000 Contacts
Per Reel)

-M
= Mini Reel
(1,000 to 5,000
Contacts Per Reel)

-B
= Bubble Bag
(35 Contacts)

View complete specifications at: samtec.com?B1SDS, samtec.com?IBT1 & samtec.com?CC508